

(FILE 'USPAT' ENTERED AT 10:52:15 ON 06 JAN 95)

L1 3725 S CONDUCTIVE (3A) ADHESIVE  
L2 64678 S INTEGRATED CIRCUIT  
L3 86184 S BATTERY  
L4 135 S L1 (P) L2  
L5 5 S L3 (P) L4

=> d 1-5

1. 5,161,304, Nov. 10, 1992, Method for packaging an electronic circuit device; Daniel Queyssac, et al., 29/827; 174/52.4; 257/676; 368/88 [IMAGE AVAILABLE]
2. 5,153,710, Oct. 6, 1992, Integrated circuit package with laminated backup cell; Joseph H. McCain, 257/724, 666, 787; 365/228, 229 [IMAGE AVAILABLE]
3. 5,089,877, Feb. 18, 1992, Zero power IC module; Daniel Queyssac, et al., 257/666; 174/52.4; 257/724; 361/730 [IMAGE AVAILABLE]
4. 5,015,830, May 14, 1991, Electronic card reading device; Shigeaki Masuzawa, et al., 235/441; 206/305; 235/380, 486; 364/705.01; D14/105 [IMAGE AVAILABLE]
5. 5,008,776, Apr. 16, 1991, Zero power IC module; Daniel Queyssac, 361/728; 257/691; 361/679; 365/229; 429/100 [IMAGE AVAILABLE]